RICHTEK®

600mA, Ultra-Low Dropout, Ultra-Fast CMOS LDO Regulator

General Description

The RT9187B is a high-performance, 600mALDO regulator, offering extremely high PSRR and ultra-low dropout. This chip is ideal for portable RF and wireless applications with demanding performance and space requirements.

A noise reduction pin is also available for further reduction of output noise. Regulator ground current increases only slightly in dropout, further prolonging the battery life. The RT9187B also works well with Iow-ESR ceramic capacitors, reducing the amount of board space necessary for power applications, critical in hand-held wireless devices.

The RT9187B consumes less than 0.1μ A in shutdown mode and has fast turn-on time for less than 40μ s. The other features include ultra-low dropout voltage, high output accuracy, current limiting protection, and high ripple rejection ratio. The RT9187B is available in the SOT-23-5 package.

Ordering Information

RT9187B

└─Package Type B : SOT-23-5 ─Lead Plating System

G : Green (Halogen Free and Pb Free)

Note :

Richtek products are :

- ▶ RoHS compliant and compatible with the current requirements of IPC/JEDEC J-STD-020.
- Suitable for use in SnPb or Pb-free soldering processes.

Marking Information

04=DNN

04= : Product Code DNN : Date Code

Features

- Ultra-Low-Noise for RF Application
- Ultra-Fast Response in Line/Load Transient
- Quick Start-Up (Typically 40µs)
- <0.1µA Standby Current When Shutdown
- Low Dropout : 100mV at 500mA
- Wide Operating Voltage Ranges : 2.5V to 5.5V
- TTL-Logic-Controlled Shutdown Input
- Current Limiting Protection
- Thermal Shutdown Protection
- Only 2.2µF Output Capacitor Required for Stability
- High Power Supply Rejection Ratio
- RoHS Compliant and Halogen Free

Applications

- CDMA/GSM Cellular Handsets
- Battery-Powered Equipment
- Laptop, Palmtops, Notebook Computers
- Hand-Held Instruments
- Mini PCI & PCI-Express Cards
- PCMCIA & New Cards
- Portable Information Appliances

Pin Configurations





Typical Application Circuit



$$V_{OUT} = 0.8 \text{ x} (1 + \frac{R_1}{R_2}) \text{ Volts}$$

Note : The value of R2 should be less than $80k\Omega$ to maintain regulation.

Function Pin Description

Pin No.	Pin Name	Pin Function		
1	VIN	Voltage Input.		
2	GND	Ground.		
3	EN	Chip Enable (Active High).		
4	ADJ	Output Voltage Feedback.		
5	VOUT	Voltage Output.		

Function Block Diagram



RICHTEK

Absolute Maximum Ratings (Note 1)

Supply Input Voltage	- 6V
EN Input Voltage	- 6V
• Power Dissipation, $P_D @ T_A = 25^{\circ}C$	
SOT-23-5	- 0.400W
Package Thermal Resistance (Note 2)	
SOT-23-5, θ _{JA}	- 250°C/W
Lead Temperature (Soldering, 10 sec.)	- 260°C
Junction Temperature	- 150°C
Storage Temperature Range	- –65°C to 150°C
ESD Susceptibility (Note 3)	
HBM	- 2kV
MM	- 200V

Recommended Operating Conditions (Note 4)

Supply Input Voltage	2.5V to 5.5V
EN Input Voltage	0V to 5.5V
Junction Temperature Range	-40°C to 125°C
Ambient Temperature Range	40°C to 85°C

Electrical Characteristics

 $(V_{IN} = V_{OUT} + 1V, V_{EN} = V_{IN}, C_{IN} = C_{OUT} = 2.2\mu F$ (Ceramic), $T_A = 25^{\circ}C$, unless otherwise specified)

Parameter		Symbol	Test Conditions	Min	Тур	Max	Unit
Reference Voltage Tolerance		V _{REF}		0.784	0.8	0.816	V
ADJ Pin Current		I _{ADJ}	$V_{ADJ} = V_{REF}$		10	100	nA
Quiescent Current (Note 5)		lq	$V_{EN} \ge V_{IH}, I_{OUT}$ = 0mA		380	500	μA
Standby Current (Note 6)		I _{STBY}	$V_{EN} \leq V_{IL}, V_{IN} = 3.3V$		0.1	1	μA
Current Limit		I _{LIM}	R _{LOAD} = 0.5Ω, V _{IN} = 3.3V	2			А
Dropout Voltage (Note 7)		V _{DROP}	I _{OUT} = 0.3A, V _{OUT} = 5V		60	100	mV
			I _{OUT} = 0.5A, V _{OUT} = 5V		100	200	
Load Regulation (Note 8)		ΔV_{LOAD}	V _{IN} = (V _{OUT} + 0.5V) 10mA < I _{OUT} < 0.5A		0.4		%/A
EN Threshold Voltage	Logic-High	V _{IH}	V _{IN} = 3.3V	1.8			V
	Logic-Low	VIL	V _{IN} = 3.3V		-	0.6	
Enable Pin Current		I _{EN}	V _{IN} = 3.3V, Enable		0.1	1	μA
Power Supply Rejection Rate	f = 100Hz	PSRR	I _{OUT} = 300mA		-60		dB
	f = 10kHz				-50		
Line Regulation		ΔV_{LINE}	V _{IN} = (V _{OUT} + 0.5) to 5.5V, I _{OUT} = 1mA		-	0.3	%
Start-Up Time		t _{Start_Up}	$R_{LOAD} = 3\Omega$		40		μs
Thermal Shutdown Temperature		T _{SD}			170		°C
Thermal Shutdown Hysteresis		ΔT_{SD}			30		

RT9187B

- **Note 1.** Stresses beyond those listed "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions may affect device reliability.
- **Note 2.** θ_{JA} is measured at $T_A = 25^{\circ}C$ on a low effective thermal conductivity single-layer test board per JEDEC 51-3.
- Note 3. Devices are ESD sensitive. Handling precaution is recommended.
- Note 4. The device is not guaranteed to function outside its operating conditions.
- Note 5. Quiescent, or ground current, is the difference between input and output currents. It is defined by $I_Q = I_{IN} I_{OUT}$ under no load condition ($I_{OUT} = 0$ mA). The total current drawn from the supply is the sum of the load current plus the ground pin current.
- Note 6. Standby current is the input current drawn by a regulator when the output voltage is disabled by a shutdown signal $(V_{EN} < 0.6V)$.
- Note 7. The dropout voltage is defined as $V_{IN} V_{OUT}$, which is measured when V_{OUT} is $V_{OUT(NORMAL)} 100 mV$.
- **Note 8.** Regulation is measured at constant junction temperature by using a 2ms current pulse. Devices are tested for load regulation in the load range from 10mA to 0.5A.

RICHTEK



RT9187B

RICHTEK



Applications Information

Output Voltage Setting

The voltage divider resistors can have values up to $80k\Omega$ because of the very high impedance and low bias current of the sense comparator. The output voltage is set according to the following equation :

 $V_{OUT} = V_{REF} \times \left(1 + \frac{R1}{R2}\right)$

where VREF is the reference voltage with a typical value of 0.8V.

Chip Enable Operation

The RT9187B goes into sleep mode when the EN pin is in a logic low condition. In this condition, the pass transistor, error amplifier, and band gap are all turned off, reducing the supply current to 1µA (max.). The EN pin can be directly tied to VIN to keep the part on.

CIN and COUT Selection

Like any low dropout regulator, the external capacitors of the RT9187B must be carefully selected for regulator stability and performance. Using a capacitor of at least 2.2µF is suitable. The input capacitor must be located at a distance of not more than 0.5 inch from the input pin of the IC. Any good quality ceramic capacitor can be used. However, a capacitor with larger value and lower ESR (Equivalent Series Resistance) is recommended since it will provide better PSRR and line transient response. The RT9187B is designed specifically to work with low ESR ceramic output capacitor for space saving and performance consideration. Using a ceramic capacitor with value at least 2.2μ F and ESR larger than $10m\Omega$ on the RT9187B output ensures stability. Nevertheless, the RT9187B can still work well with other types of output capacitors due to its wide range of stable ESR. "Typical Operating Characteristics" shows the allowable ESR range as a function of load current for various output capacitance. Output capacitors with larger capacitance can reduce noise and improve load transient response, stability, and PSRR. The output capacitor should be located at a distance of not more than 0.5 inch from the output pin of the RT9187B.

Thermal Considerations

For continuous operation, do not exceed absolute maximum junction temperature. The maximum power dissipation depends on the thermal resistance of the IC package, PCB layout, rate of surrounding airflow, and difference between junction and ambient temperature. The maximum power dissipation can be calculated by the following formula :

$P_{D(MAX)} = (T_{J(MAX)} - T_A) / \theta_{JA}$

where $T_{J(MAX)}$ is the maximum junction temperature, T_A is the ambient temperature, and θ_{JA} is the junction to ambient thermal resistance.

For recommended operating condition specifications, the maximum junction temperature is 125°C. The junction to ambient thermal resistance, θ_{JA} , is layout dependent. For SOT-23-5 packages, the thermal resistance, θ_{JA} , is 250° C/ W on a standard JEDEC 51-3 single-layer thermal test board. The maximum power dissipation at $T_A = 25^{\circ}C$ can be calculated by the following formula :

 $P_{D(MAX)} = (125^{\circ}C - 25^{\circ}C) / (250^{\circ}C/W) = 0.400W$ for

SOT-23-5 package

The maximum power dissipation depends on the operating ambient temperature for fixed $T_{J(MAX)}$ and thermal resistance, θ_{JA} . The derating curve in Figure 1 allows the designer to see the effect of rising ambient temperature on the maximum power dissipation.



